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EMASS Sponsors AI Everywhere Conference Highlighting Edge AI Innovation

Virtual event explores ultra-low-power AI chips, TinyML, and next-generation inference at the edge

LOS ANGELES (Dec. 4, 2025) – EMASS, a Nanoveu subsidiary with next-generation semiconductor technology, announced its participation and sponsorship in EETimes' AI Everywhere event, held virtually, December 10 and 11. The conference will feature engineering-driven sessions including keynotes, panel discussions and technical presentations exploring the latest advancements in AI architectures, chiplet design, inference efficiency and edge-to-cloud system performance.

EMASS chose to sponsor the event in alignment with the company's mission to advance the field of what's possible at the edge. The symposium's focus on inference efficiency, model portability, and system-level design mirrors EMASS' work delivering always-on intelligence within strict milliwatt and latency constraints.

"AI Everywhere is exactly where EMASS lives; at the edge, where every milliwatt and millisecond counts," said Mark Goranson, CEO of EMASS. "We're excited to support this EE Times event and engage with engineers who are pushing the boundaries of what's possible in always-on, battery-powered AI."

To learn more about the event, visit the AI Everywhere website.

EMASS' recent collaborations, events and developments highlight the capability of the ECS-DoT SoC, which delivers ultra-low-power, low-latency AI compute for vision, audio and multimodal sensor workloads. These advancements highlight growing industry demand for efficient on-device inference as model complexity increases across embedded, wearable, and industrial systems. To learn more about recent EMASS news, visit the website.

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About EMASS

EMASS – a subsidiary of Nanoveu Ltd (ASX: NVU) – is an advanced semiconductor company specializing in ultra-low-power AI system-on-chip (SoC) solutions for edge computing. The company's flagship ECS-DoT chip delivers high-performance AI processing for vision, audio, and sensor data directly on-device, maximizing energy efficiency through its RISC-V architecture and non-volatile memory technologies. This always-on intelligence solution is optimized for power- and space-constrained applications including drones, wearables, healthcare devices and industrial IoT systems. For more information, visit nanoveu.com/emass.

About Nanoveu

Nanoveu is a listed company advancing human–machine experiences at the edge through a portfolio that spans ultra-low-power AI and glasses-free 3D technologies. Its subsidiary EMASS designs advanced system-on-chip (SoC) solutions that deliver efficient, scalable on-

device AI for smart devices, IoT applications and 3D content transformation – enhancing Nanoveu's reach across rapidly growing AI, edge computing and 3D content markets. EyeFly3D™ is Nanoveu's end-to-end platform for glasses-free 3D, uniting proprietary screen technology with sophisticated content processing software and, now, EMASS's ultra-low-power SoC to bring immersive 3D to a wide range of devices and industries. The Company also develops and markets an advanced range of self-disinfecting and hydrophobic films and coatings under the Nanoshield™ brand, designed for applications including large-scale CSP and photovoltaic solar installations. Together, Nanoveu's businesses deliver practical innovation that makes devices smarter, environments safer and experiences more immersive.

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